

PRELIMINARY SPEC

Part Number: KPT-1608LSURCK

HYPER RED

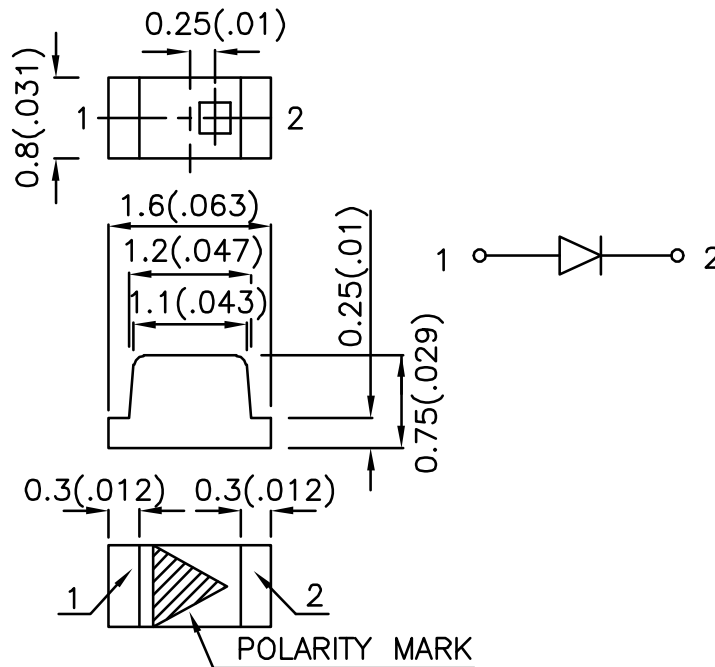
Features

- 1.6mmX0.8mm SMT LED, 0.75mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE: 2000PCS / REEL.
- LOW CURRENT IF=2mA OPERATING.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Typ.	2 θ 1/2
KPT-1608LSURCK	HYPER RED (InGaAlP)	WATER CLEAR	3	15	120°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous Intensity / Luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Hyper Red	650		nm	IF=20mA
$\lambda_D[1]$	Dominant Wavelength	Hyper Red	635		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
C	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF[2]	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
IR	Reverse Current	Hyper Red		10	uA	VR = 5V

Notes:

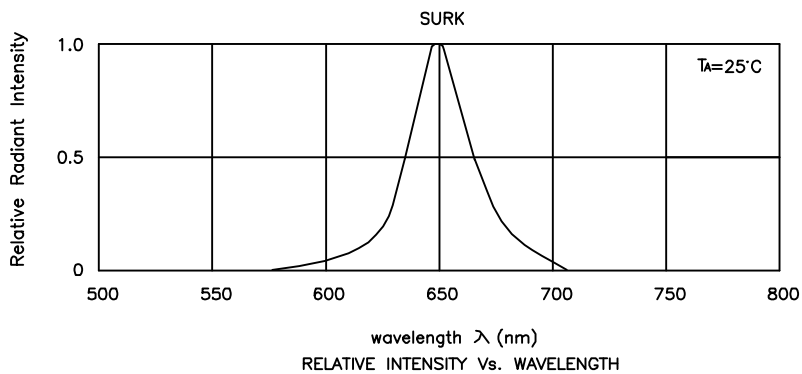
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

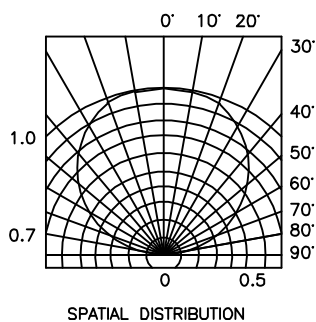
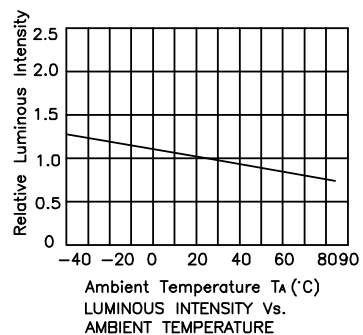
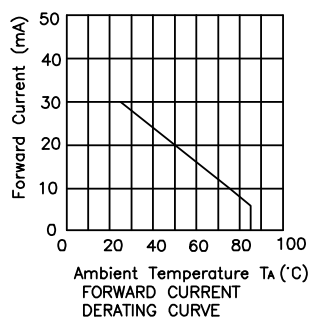
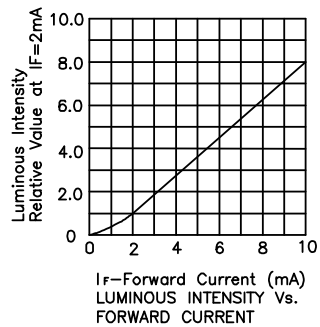
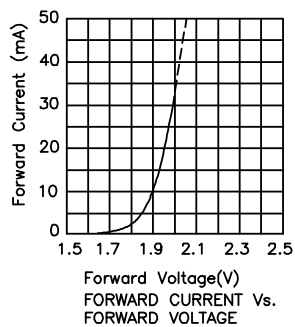
Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating / storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

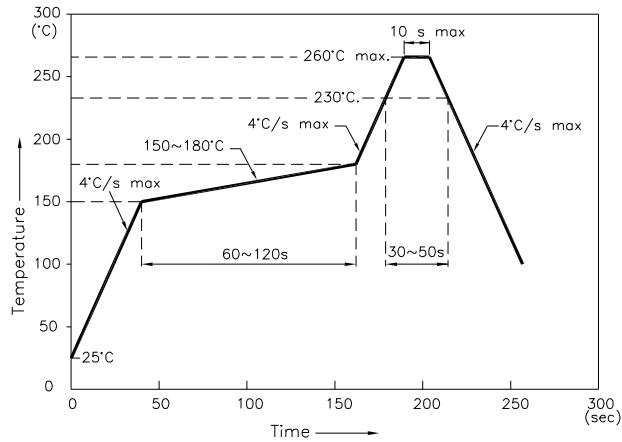


KPT-1608LSURCK Hyper Red



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Reflow Soldering Profile For Lead-free SMT Process.

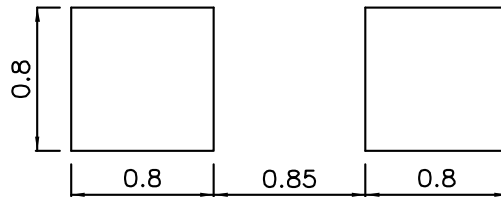


NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units : mm; Tolerance: ± 0.1)



Tape Specifications

(Units : mm)

